

PART INFORMATION

Mfg Item Number	MCIMX6Q5EYM12AD
Mfg Item Name	FCPBGA 624 21*21*1.45P.8

SUPPLIER

Company Name	Freescale Semiconductor Inc
Company Unique ID	14-141-7928
Response Date	2017-09-05
Response Document ID	009UK00227D002A1.6
Contact Name	Freescale Semiconductor Inc
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DECLARATION

EU RoHS	Yes
Pb Free	Yes
HalogenFree	Yes
Plating Indicator	e1
EU RoHS Exemption(s)	

MANUFACTURING

Mfg Item Number	MCIMX6Q5EYM12AD
Mfg Item Name	FCPBGA 624 21*21*1.45P.8
Version	ALL
Weight	1.287100
UoM	g
Unit Volume	EACH
J-STD-020 MSL Rating	3
Peak Processing Temperature	260 C
Max Time at Peak Temperature	40 seconds
Number of Processing Cycles	3

RoHS	
RoHS Directive	2011/65/EU
RoHS Definition	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) of homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material of Cadmium
RoHS Legal Definition	Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part(s) identified on this form contains lead, mercury, cadmium, hexavalent chromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a RoHS restricted substance) in excess of the applicable quantity limit identified below. If a homogeneous material within the part(s) contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Suppliers liability and the Companys remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppliers Standard Terms and Conditions of Sale applicable to such part(s) shall apply.
RoHS Declaration	1 - Item(s) do not contain RoHS restricted substances per the definition above
Supplier Acceptance	Accepted
Signature	Daniel Binyon
Exemption List Version	2012/51/EU
List of Freescale Accepted Exemptions	<p>6(a) : Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight</p> <p>6(b) : Lead as an alloying element in aluminium containing up to 0.4% lead by weight</p> <p>6(c) : Copper alloy containing up to 4% lead by weight</p> <p>7(a) : Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead)</p> <p>7(b) : Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission, and network management for telecommunications</p> <p>7(c)-I : Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectric devices, or in a glass or ceramic matrix compound</p> <p>7(c)-II : Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher</p> <p>7(c)-III : Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC</p> <p>7(c)-IV : Lead in PZT based dielectric ceramic materials for capacitors being part of integrated circuits or discrete semiconductors</p> <p>15 : Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages</p>

MATERIAL COMPOSITION

Homogeneous Material	Weight	SubstanceClass	Substance	CAS	Exemption	SubstanceWeight	UoM	SubPart PPM	SubPart%	ARTICLEPPM	ARTICLE%
Underfill	0.012						g				
Underfill		Solvents, additives, and other materials	4,4'-Diamino-3,3'-diethyl-diphenylmethane	19900-65-3		0.00132	g	110000	11	1025	0.1025
Underfill		Bismuth/Bismuth Compounds	Bismuth nitrate	10361-44-1		0.000012	g	1000	0.1	9	0.0009
Underfill		Bismuth/Bismuth Compounds	Bismuth trioxide	1304-76-3		0.000096	g	8000	0.8	74	0.0074
Underfill		Plastics/polymers	1,6-Bis(2,3-epoxypropoxy) naphthalene	27810-48-6		0.00168	g	140000	14	1305	0.1305
Underfill		Plastics/polymers	Phenolic Polymer Resin, Epikote 155	9003-36-5		0.0012	g	100000	10	932	0.0932
Underfill		Solvents, additives, and other materials	Carbon Black	1333-86-4		0.000012	g	1000	0.1	9	0.0009
Underfill		Plastics/polymers	4,4'-isopropylidenediphenol-1-chloro-2,3-epoxypropane concentrate	25068-38-6		0.00048	g	40000	4	372	0.0372
Underfill		Glass	Silica, vitreous	60676-86-0		0.0072	g	600000	60	5593	0.5593
Solder Balts - Lead Free	0.3172						g				
Solder Balts - Lead Free		Metals	Copper, metal	7440-50-8		0.01441833	g	45455	4.5455	11202	1.1202
Solder Balts - Lead Free		Metals	Silver, metal	7440-22-4		0.00940308	g	29644	2.9644	7305	0.7305
Solder Balts - Lead Free		Metals	Tin, metal	7440-31-5		0.29337659	g	924901	92.4901	227937	22.7937
Organic Substrate	0.9189						g				
Organic Substrate		Metals	Barium sulfate	7727-43-7		0.01474559	g	16982	1.6982	11456	1.1456
Organic Substrate		Metals	Copper, metal	7440-50-8		0.30260093	g	330029	33.0029	235115	23.5115
Organic Substrate		Plastics/polymers	Epikote 862	28964-14-4		0.88413108	g	91756	9.1756	65364	6.5364
Organic Substrate		Plastics/polymers	Formaldehyde, polymer with 2-methylphenol, glycidyl ether	64425-89-4		0.02294548	g	24916	2.4916	17749	1.7749
Organic Substrate		Lead/Lead Compounds	Lead	7439-92-1		0.00034384	g	375	0.0375	267	0.0267
Organic Substrate		Plastics/polymers	Phenol, polymer with formaldehyde	9003-35-4		0.04594219	g	50106	5.0106	35694	3.5694
Organic Substrate		Glass	Fibrous-glass-wool	65997-17-3		0.28139386	g	306897	30.6897	218626	21.8626
Organic Substrate		Glass	Silicon dioxide	7631-86-9		0.02411905	g	26305	2.6305	18739	1.8739
Organic Substrate		Metals	Tin, metal	7440-31-5		0.00058498	g	638	0.0638	454	0.0454
Organic Substrate		Solvents, additives, and other materials	Other Aromatic carbonyl compounds	-		0.00236744	g	2582	0.2582	1839	0.1839
Organic Substrate		Metals	Aluminum Hydroxide	21645-51-2		0.13782566	g	150317	15.0317	107082	10.7082
Pb-free Bumped Semiconductor D	0.041						g				
Pb-free Bumped Semiconductor D		Nickel (external applications only)	Nickel	7440-02-0		0.000205	g	5000	0.5	159	0.0159
Pb-free Bumped Semiconductor D		Metals	Silver, metal	7440-22-4		0.00012915	g	3150	0.315	100	0.01
Pb-free Bumped Semiconductor D		Metals	Tin, metal	7440-31-5		0.00356085	g	86850	8.685	2766	0.2766
Pb-free Bumped Semiconductor D		Solvents, additives, and other materials	Other miscellaneous substances (less than 5%)	-		0.000369	g	9000	0.9	286	0.0286
Pb-free Bumped Semiconductor D		Glass	Silicon, doped	-		0.036736	g	886000	88.6	28541	2.8541

LINKS

MCD LINK	
NXP website	http://www.nxp.com
GENERAL ENVIRONMENTAL COMPLIANCE LINKS	
RoHS signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ROHS-DECLARATION.pdf
China RoHS	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/china-rohs:ENV_CHINA_ROHS_STRATEGY
REACH signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-REACH-STATEMENT.pdf
ELV signed letter	http://www.nxp.com/files/corporate/doc/support_info/NXP-ELV-STATEMENT.pdf
Conflict Minerals statement	http://www.nxp.com/files/corporate/doc/support_info/NXP-STATEMENT-CONFLICT-MINERALS.pdf
NXP ENVIRONMENTAL INFORMATION	
Environmental Compliance website	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization:ABUENVPRFPRDX
FAQ	http://www.nxp.com/about/corporate-responsibility/environmental-compliance-organization/eco-product-faqs:ENVIRON_FAQ
Technical Service Request	http://www.nxp.com/support/sales-and-support:SUPPORTHOME
LINKS TO BLANK IPC1752 FORMS	
Blank IPC1752 v1.1 Form	http://www.NXP.com/files/abstract/corporate/ehs_epp/IPC-1752-2_v1.1_MCD_Template.pdf

IPC1752 XML LINKS

http://www.freescale.com/mcdfs/MCIMX6Q5EYM12AD_IPC1752_v11.xml

http://www.freescale.com/mcdfs/MCIMX6Q5EYM12AD_IPC1752A.xml